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(12) **United States Design Patent**
Green et al.

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(54) **SUBSTRATE PROCESSING SYSTEM CARRIER**

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(**) Term: **15 Years**

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Primary Examiner — Shawn T Gingrich

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(74) *Attorney, Agent, or Firm* — Lowenstein Sandler LLP

(51) **LOC (14) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/123, 133, 146, 147, 158, 182, 184,
D13/199, 149, 151, 154, 173
CPC H01R 13/42; H01R 13/436; H01R 13/52;
H01R 13/53; H01R 13/64; H01R 13/648;
H01R 13/73; H01R 24/20; B25J 15/08;
B65G 47/90; H01L 21/672; H01L 21/673;
H01L 21/67379; H01L 21/67383; H01L
21/677

See application file for complete search history.

(57) **CLAIM**

The ornamental design for a substrate processing system carrier, as substantially shown and described.

DESCRIPTION

FIG. 1 shows a top perspective view of a substrate processing system carrier in accordance with the present invention; FIG. 2 shows a bottom perspective view thereof; FIG. 3 shows a top plan view thereof; FIG. 4 shows a bottom plan view thereof; FIG. 5 shows a left side elevation view thereof; FIG. 6 shows a right side elevation view thereof; FIG. 7 shows a front elevation view thereof; FIG. 8 shows a rear elevation view thereof; FIG. 9 shows a top perspective view thereof in its intended environment; and, FIG. 10 shows a top perspective view thereof in its intended environment.

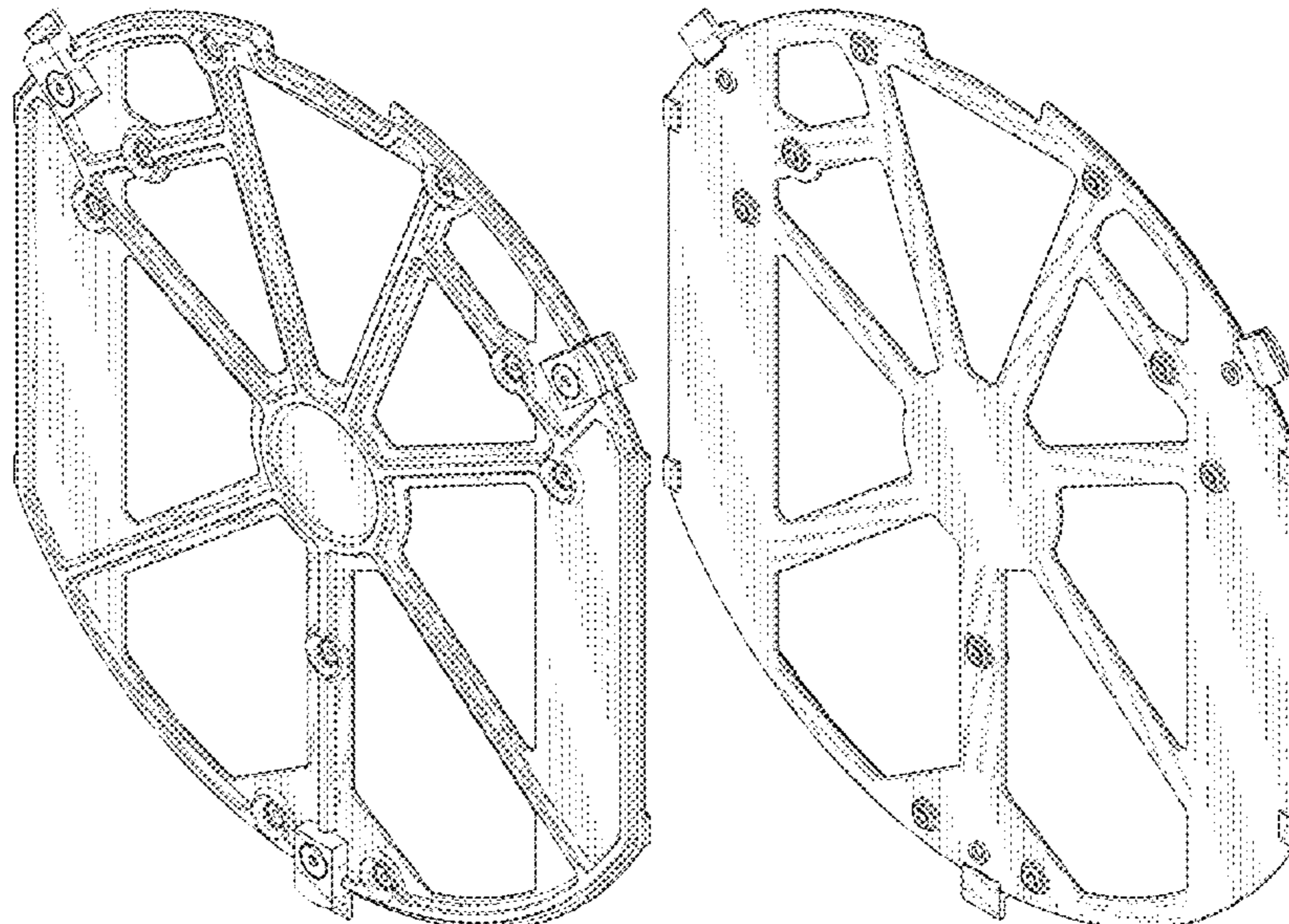
The broken lines in the drawings illustrate environment that forms no part of the claimed design.

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1 Claim, 8 Drawing Sheets



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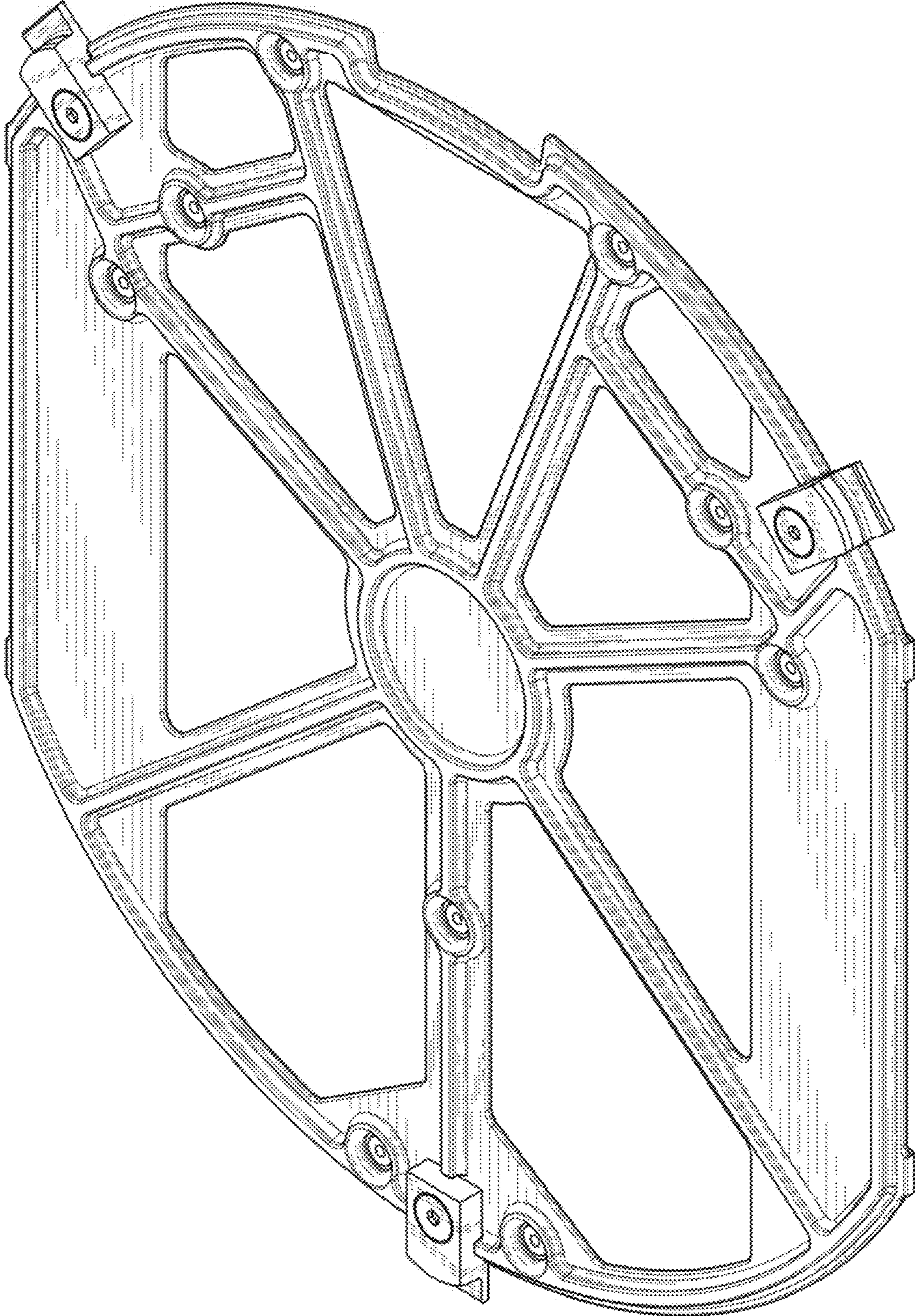


FIG. 1

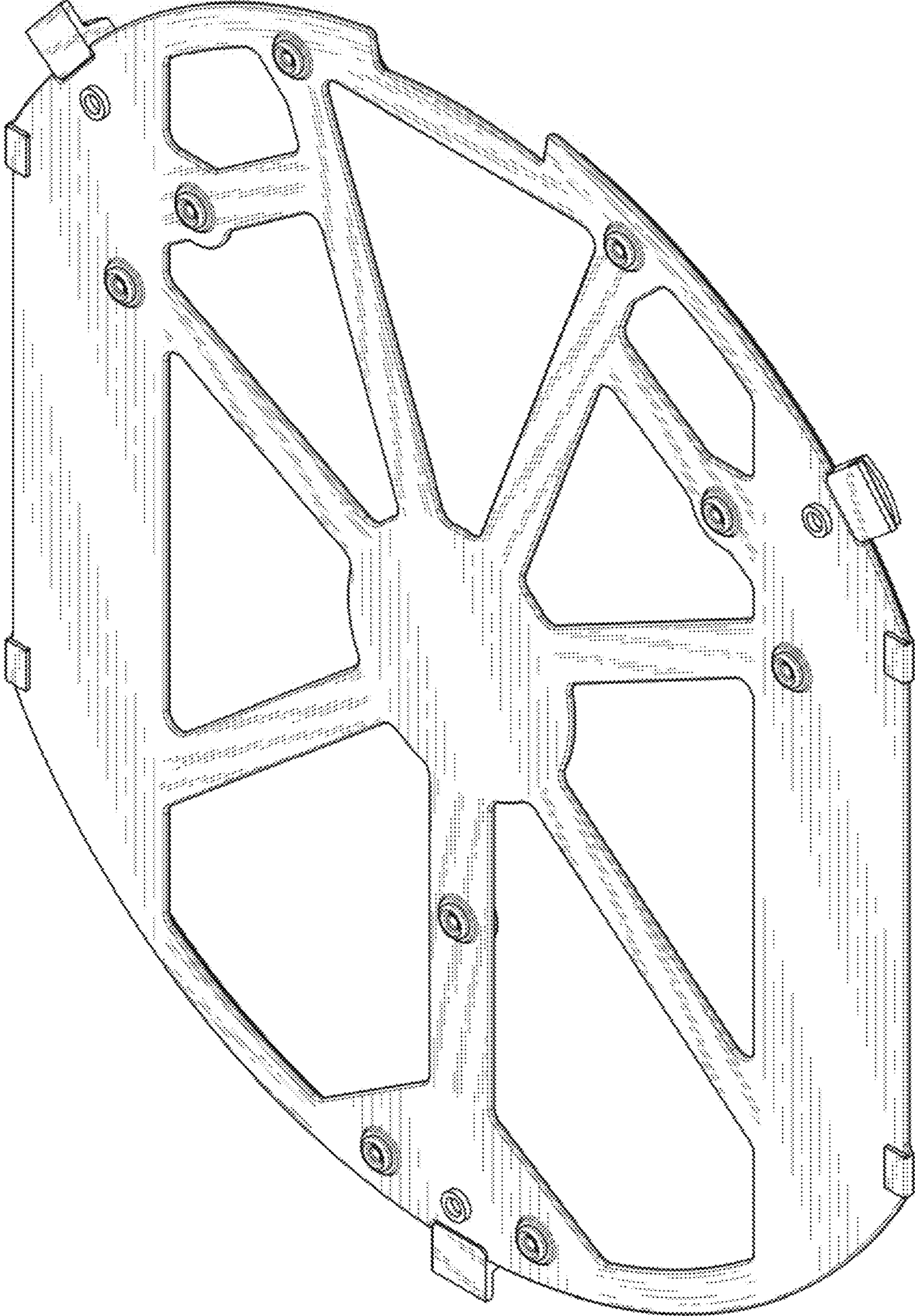


FIG. 2

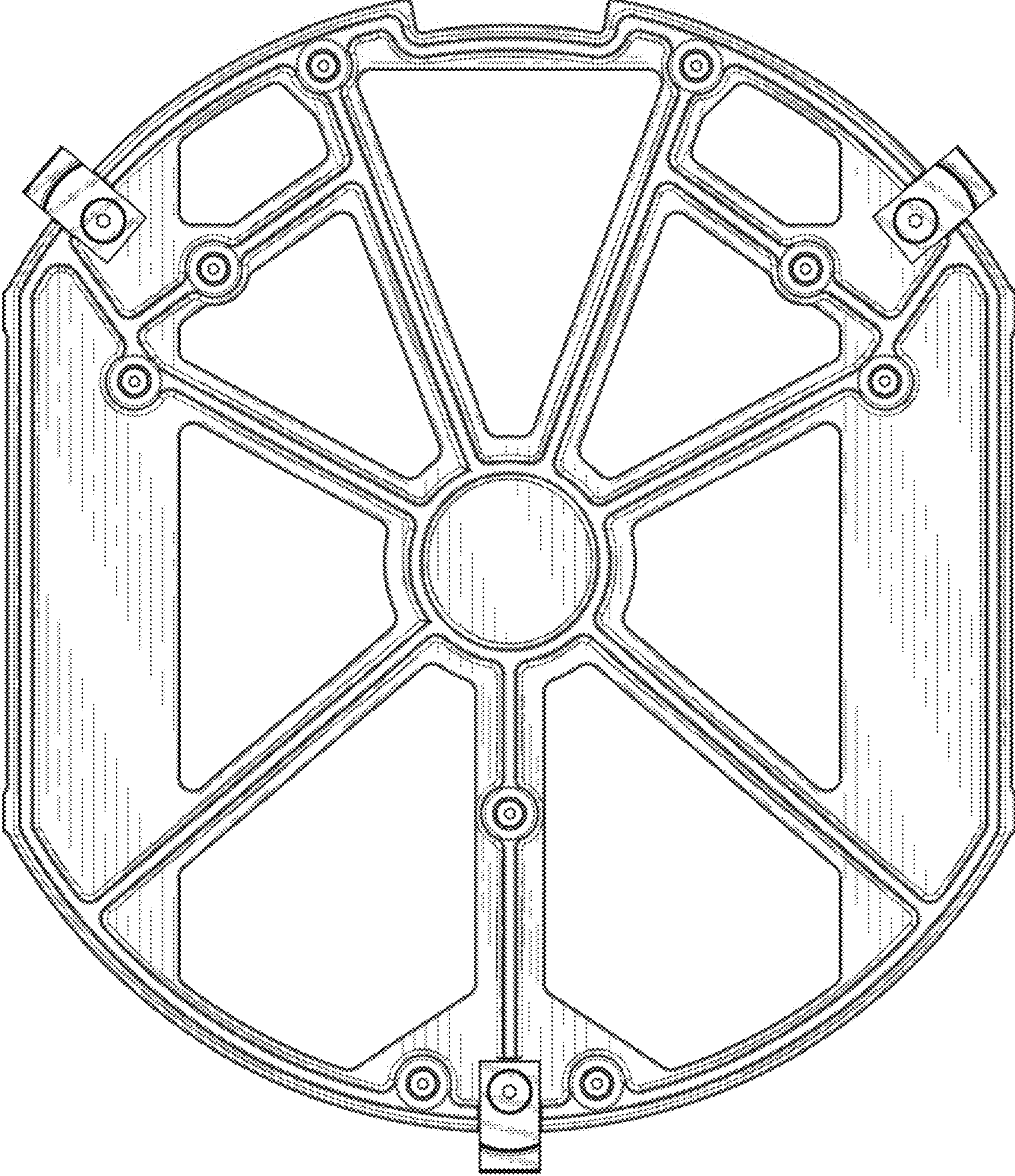


FIG. 3

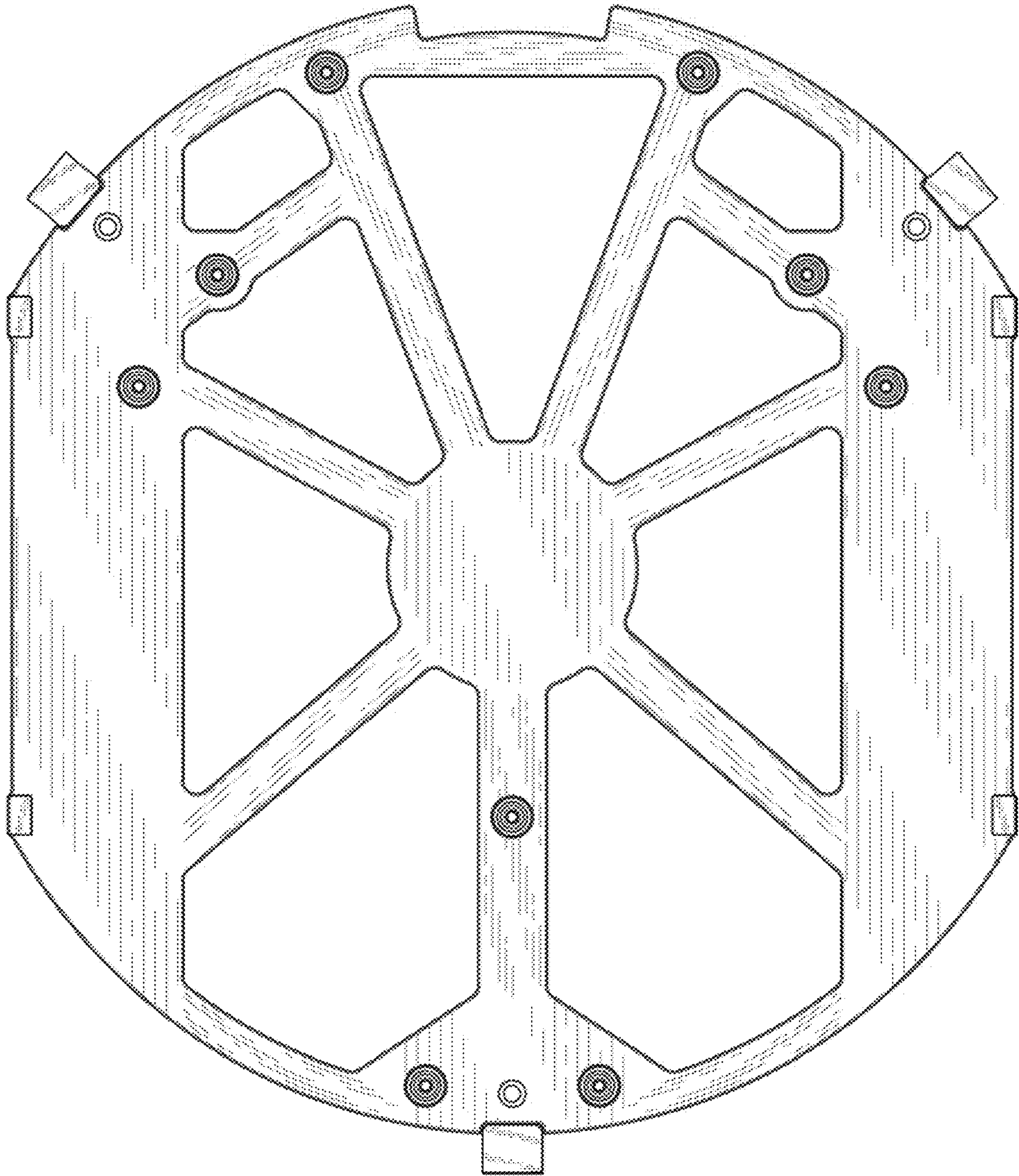


FIG. 4

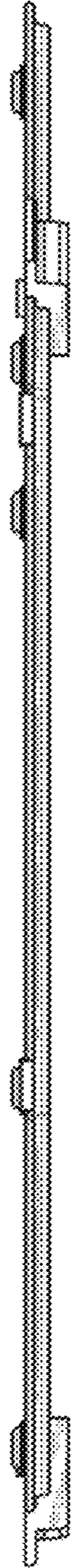


FIG. 5

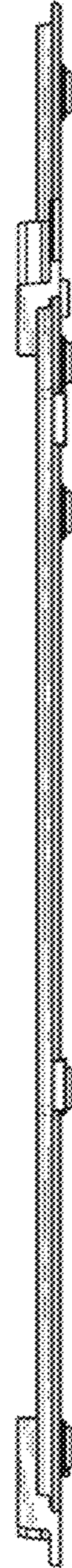


FIG. 6



FIG. 7



FIG. 8

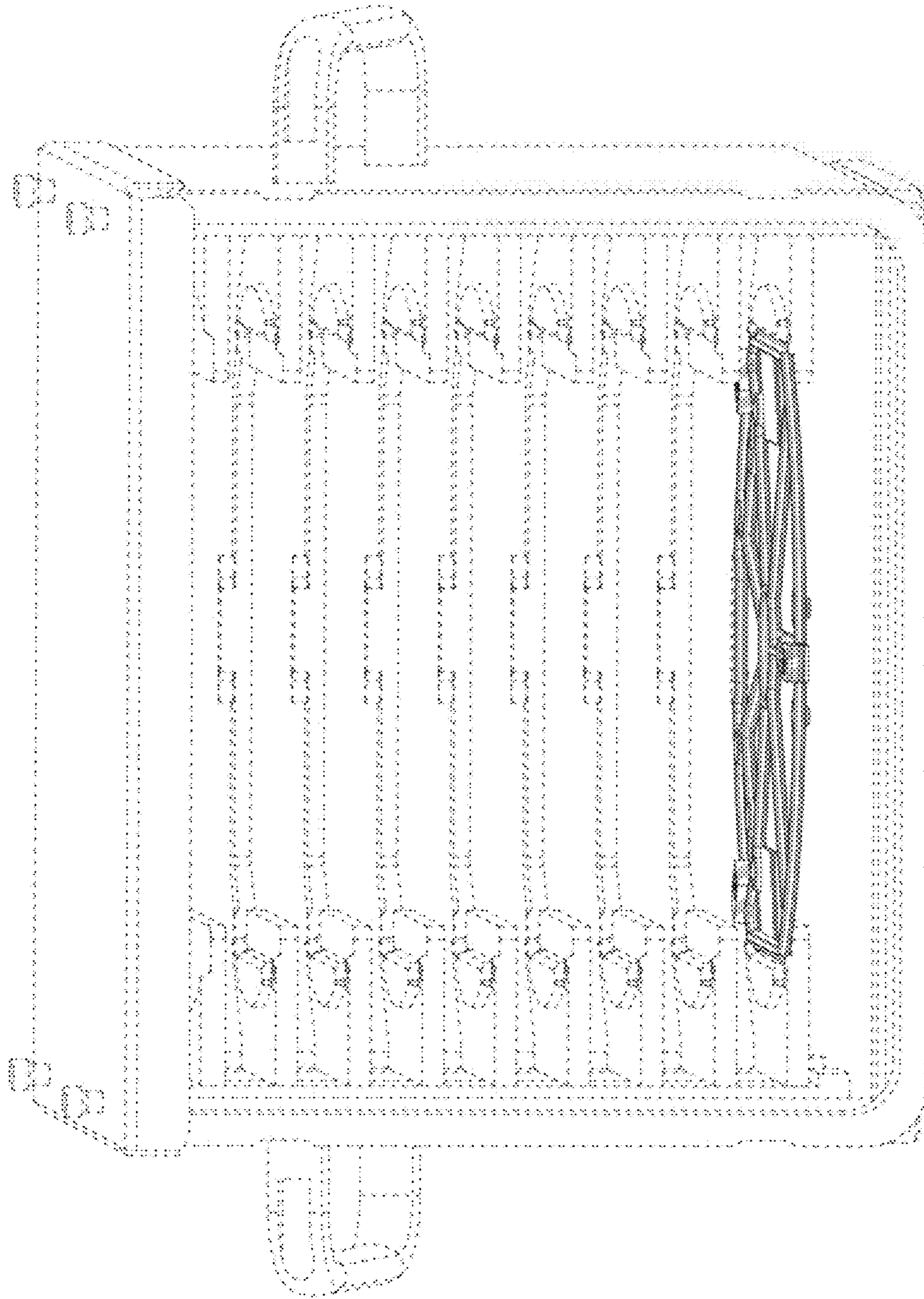


FIG. 9

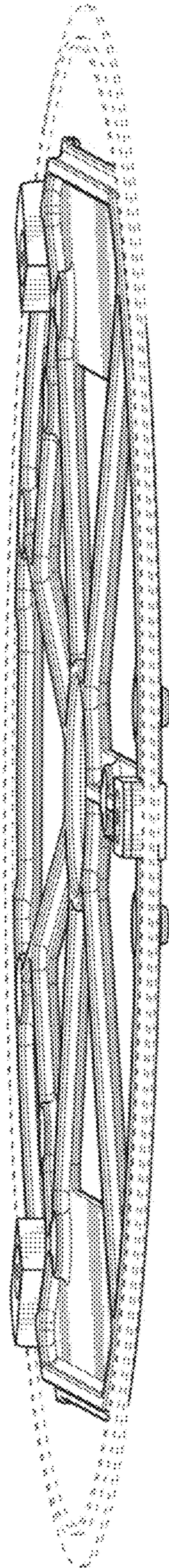


FIG. 10